

Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A method of repairing a patterned seat surface of a pedestal surface, comprising the step of polishing said patterned seat surface using a coarse surface of a film.
2. (Original) A method according to claim 1, wherein the film has a coarseness of from 1 to 45 microns.
3. (Currently Amended) A method of repairing a patterned seat surface of a pedestal surface, comprising the step of polishing said patterned seat surface using a coarse surface with a coarseness of from 1 to 45 microns.
4. (Original) A method according to claim 3, wherein the coarse surface is a coarse surface of a film.
5. (Previously Presented) A method according to claim 1, wherein the film is mounted on one side of a silicon wafer.

6. (Original) A method according to claim 5, wherein the film is mounted on the silicon wafer using a mineral oil as an adhesive.
7. (Original) A method according to claim 6, wherein the mineral oil is a fluorinated oil
8. (Currently Amended) A method according to claim 5, wherein the other side of the silicon wafer from the coarse surface has tape thereon to ~~provide an improved grip~~ hold up loose wafer chips in an event of breakage of the silicon wafer.
9. (Currently Amended) A method according to claim 1, further comprising the step of applying ~~IPA~~ isopropyl alcohol between the coarse surface and the ~~pedestal~~ patterned seat surface prior to polishing.
10. (Previously Presented) A method according to claim 1, wherein the coarse surface comprises diamond grains.
11. (Previously Presented) A method according to claim 1, wherein the pedestal is a heater pedestal.
12. (Currently Amended) A method according to claim 1, wherein the pedestal is a pedestal for

use in CVD, PVD, metal / oxide etching, photolithographic scanning or semiconductor processing, said processing requiring one or more of a group consisting of that requires heating, or a vacuum, or and mechanical devices to secure the position of a wafer to the pedestal patterned seat surface.

13. (Cancelled).

14. (Cancelled).